



## Inkjet Printing for Materials and Devices

Guest Editor:

**Prof. Dr. Silvia Schintke**

Laboratory of Applied  
NanoSciences (COMATEC-LANS),  
Department of Industrial  
Technologies, HEIG-VD, HES-SO,  
University of Applied Sciences  
and Arts Western Switzerland,  
CH-1401 Yverdon-les-Bains,  
Switzerland

Deadline for manuscript  
submissions:

**closed (30 June 2021)**

### Message from the Guest Editor

The aim of this Special Issue is to bring together researchers working on applications of novel inkjet-printable materials and devices, both at the advanced materials side and at the innovative printing and processing technologies side. The Special issue aims to provide novel insights into technical processes, instrumentation, and applications of inkjet printing and related technologies for advanced printable materials and devices. Both experimental studies and theoretical or numerical ink flow or print-process modeling for inkjet printing and related solution-based dispensing, printing, and additive manufacturing technologies for advanced printable materials and devices are welcome.

In this Special Issue we welcome both original research papers and review articles on diverse topics such as:

- inkjet printing
- solution-based processing
- additive manufacturing
- hybrid inks
- composites
- smart hydrogels
- printing process and technologies
- process modeling
- printed electronics
- flexible devices





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## Editor-in-Chief

**Prof. Dr. Giulio Nicola Cerullo**  
Dipartimento di Fisica,  
Politecnico di Milano, Piazza L.  
da Vinci 32, 20133 Milano, Italy

## Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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*Applied Sciences* Editorial Office  
MDPI, Grosspeteranlage 5  
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